



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# Chip™ Fuses

## 3216TD Series, Time-Delay



### Description

- Time-delay, surface mount fuse
- RoHS compliant and Lead Free
- High inrush withstand capability
- Wire-in-Air performance
- Compatible with leaded and lead-free reflow and wave solder



### Agency Information

- **UL** Recognition File number: E19180

### Environmental Data

- Operating temperature range: -55°C to 125°C with proper derating
- Vibration: MIL-STD-202, Method 204 Condition D
- Solderability: ANSI/J-STD-002C, Test B

### Ordering

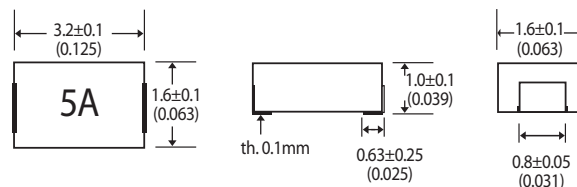
- Specify packaging and product code (i.e., TR/3216TD1-R)

### Soldering Method

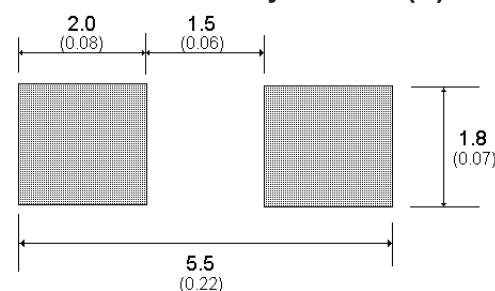
- Wave immersion: 260°C, 10 Sec. max.
- Infrared reflow: 260°C, 30 Sec. max.
- Hand solder: 350°C, 3 Sec. max.

### Dimensions - mm (in)

Drawing Not to Scale



### Recommended Pad Layout - mm (in)



Electrical Characteristics	
% of Amp Rating	Opening Time
100%	4 Hours Minimum
200%	1 Sec. Minimum, 120 Sec. Maximum
300%	0.05 Sec. Minimum, 3 Sec. Maximum
800%	0.002 Sec. Minimum, 0.05 Sec. Maximum

Specifications								
Product Code	Current Rating Amps	Voltage Rating		Interrupting Rating (Amps)*		Resistance (Ω)** Typ.	Typical Melt I <sup>††</sup> DC	Typical Voltage Drop (V)‡
		Vac	Vdc	AC	DC			
3216TD500-R	0.5	63	32	50	35	0.150	0.064	75
3216TD750-R	0.75	63	32	50	35	0.100	0.12	75
3216TD800-R	0.8	63	32	50	35	0.087	0.16	75
3216TD1-R	1	63	32	50	35	0.075	0.32	75
3216TD1.5-R	1.5	32	32	35	35	0.050	0.62	75
3216TD2-R	2	32	32	35	35	0.030	1.30	60
3216TD2.5-R	2.5	32	32	35	35	0.022	2.25	55
3216TD3-R	3	32	32	35	35	0.018	3.30	55
3216TD4-R	4	32	32	35	35	0.0165	5.20	56
3216TD5-R	5	32	32	35	35	0.015	8.40	66
3216TD6.3-R	6.3	32	32	35	35	0.0120	13.8	75
3216TD7-R	7	32	32	35	35	0.0095	18.0	67
3216TD8-R	8	32	32	35	35	0.0083	38.0	65
3216TD10-R	10	32	32	35	35	0.006	54.4	65
3216TD12-R	12	32	32	35	35	0.005	64.0	65

\* AC Interrupting Rating (Measured at rated voltage with a unity power factor); DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)

\*\* DC Cold Resistance (Measured at 10% of rated current)

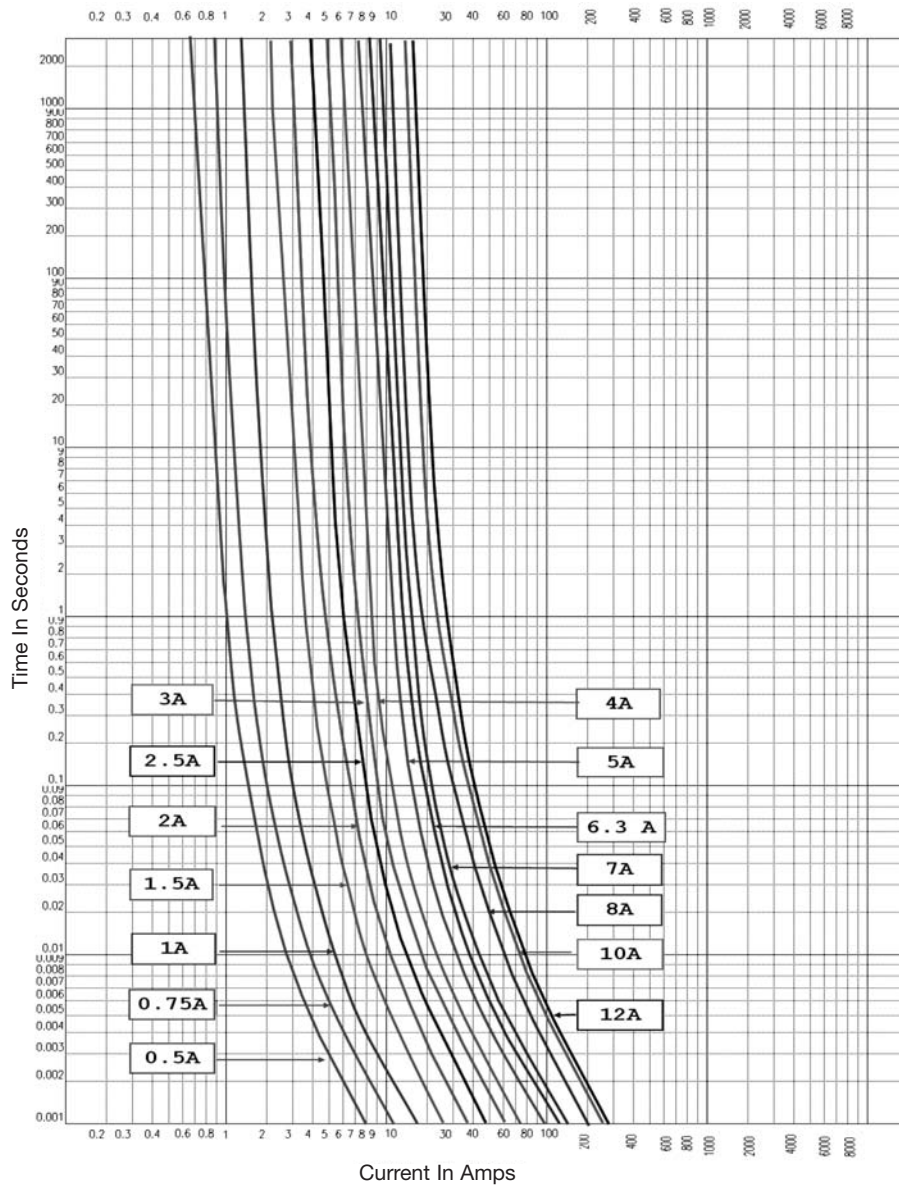
† Typical Melting I<sup>†</sup> (Measured with a battery bank at rated DC voltage, 10x-rated current at 1 microsecond, not to exceed IR. Above 7A uses 70 micron thickness copper layer test board of IEC 60127-3. Others uses 35 micron thickness copper layer.

‡ Typical Voltage Drop (Measured at rated current after temperature stabilizes)

Device designed to carry rated current for four hours minimum. An operating current of 80% or less of rated current is recommended, with further derating required at elevated ambient temperatures.



## Time-Current Curves



### Packaging

Packaging Code Prefix	Description
TR	2,500 fuses on 12mm tape-and-reel on a 180mm reel per EIA-481-A & IEC286-3

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